



## Features

- Designed size of 1812 & 2920
- Fast tripping resettable circuit protection
- Surface mount packaging for automated assembly
- Agency recognition: UL, CSA, TUV

**SEL-USE**



## LP-SM series

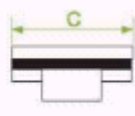
Surface-mount devices

## Product Dimensions

Part number	A	B	C	D
	Max.	Max.	Max.	Max.
LP-SM030	7.98	3.18	5.44	0.70
LP-SM050	7.98	3.18	5.44	0.70
LP-SM075	7.98	3.18	5.44	0.70
LP-SM110	7.98	3.00	5.44	0.70
LP-SM125	9.50	3.00	5.00	0.70
LP-SM130	9.50	3.00	6.71	0.70
LP-SM150	9.50	3.00	6.71	0.70
LP-SM185	9.50	3.00	6.71	0.70
LP-SM200	9.50	3.00	6.71	0.70
LP-SM250	7.98	3.18	6.71	0.70
LP-SM260	7.98	3.18	5.44	0.70
LP-SM300	7.98	3.18	5.44	0.70



Side View



End View

## Part Marking System



Current rating

Wayon symbol

## Electrical Characteristics

Part number	$I_H$	$I_T$	$V_{max}$	$I_{max}$	$T_{trip}$		$Pd_{typ}$	$R_{min}$	$R_{1max}$
	(A)	(A)	(V)	(A)	Current(A)	Time(S)	(W)	( )	( )
LP-SM030	0.30	0.60	60	10	1.5	4.0	1.9	0.700	4.80
LP-SM050	0.50	1.00	60	10	2.5	4.0	1.9	0.350	1.400
LP-SM075	0.75	1.50	60	40	8.0	3.0	1.9	0.290	1.000
LP-SM110	1.10	2.20	33	40	8.0	0.20	1.9	0.100	0.480
LP-SM125	1.25	2.50	24	40	8.0	0.20	1.6	0.070	0.250
LP-SM130	1.30	2.60	33	40	8.0	4.0	2.1	0.080	0.280
LP-SM150	1.50	3.00	33	40	8.0	5.0	2.1	0.060	0.250
LP-SM185	2.00	3.70	15	40	8.0	5.0	2.1	0.045	0.165
LP-SM200	2.50	4.00	15	40	8.0	12.0	2.1	0.045	0.125
LP-SM250	2.60	5.00	15	40	8.0	25.0	1.9	0.025	0.085
LP-SM260	3.00	5.20	6	40	8.0	20.0	1.9	0.025	0.075
LP-SM300	2.60	6.00	6	40	8.0	35.0	1.9	0.015	0.048

$I_H$ =Hold current: maximum current at which the device will not trip at 25 °C still air.

$I_T$ =Trip current: minimum current at which the device will always trip at 25 °C still air.

$V_{max}$ =Maximum voltage device can withstand without damage at rated current.

$I_{max}$ =Maximum fault current device can withstand without damage at rated voltage.

$T_{trip}$ =Maximum time to trip at assigned current.

$Pd_{typ}$ =Typical power dissipation: typical amount of power dissipated by the device when in state air environment.

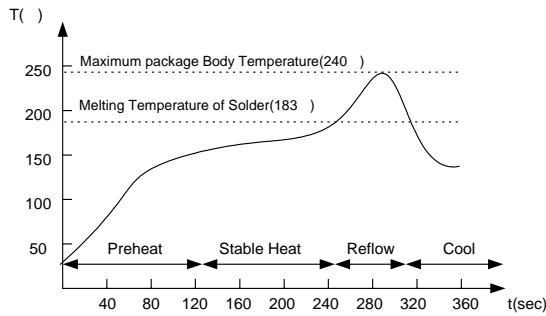
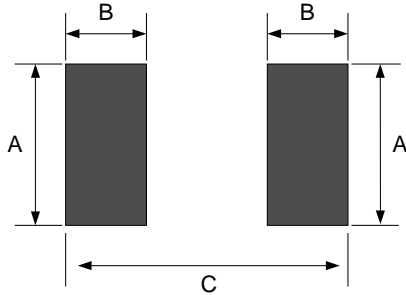
$R_{min}$ =Minimum device resistance at 25 °C prior to tripping.

$R_{1max}$ =Maximum device resistance measured in the nontripped state 1 hour post reflow.

## Test Procedures And Requirements

Test	Test Conditions	Accept/Reject Criteria
Resistance	In still air @ 25	$R_{min}$ R $R_{max}$
Time to Trip	Specified current, $V_{max}$ , 25	T maximum Time to Trip
Hold Current	30min, at $I_H$	No trip
Trip Cycle Life	$V_{max}$ , $I_{max}$ , 100cycles	No arcing or burning
Trip Endurance	$V_{max}$ , 24hours	No arcing or burning

## Solder Reflow Recommendations



### Solder Pad Layouts

Part number	A (mm)	B (mm)	C (mm)
LP-SM030	3.1	2.3	9.7
LP-SM050	3.1	2.3	9.7
LP-SM075	3.1	2.3	9.7
LP-SM110	3.1	2.3	9.7
LP-SM125	3.1	2.3	9.7
LP-SM130	4.6	2.3	10.7
LP-SM150	4.6	2.3	10.7
LP-SM185	4.6	2.3	10.7
LP-SM200	4.6	2.3	10.7
LP-SM250	4.6	2.3	10.7
LP-SM260	3.1	2.3	9.7
LP-SM300	3.1	2.3	9.7

\* Recommended reflow methods: IR, Vapor phase oven, hot air oven, wave solder.

\* Devices can be cleaned using standard industry methods and solvents.

#### Notes:

If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

## Package Information

Tape & Reel: 2000pcs per reel.

#### Notices:

The devices are intended for protection against occasional overcurrent or overtemperature fault conditions and should not be used when repeated fault conditions are anticipated.

Operation beyond maximum ratings or improper use may result in device damage and possible electrical arcing and flame.